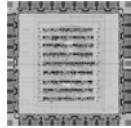
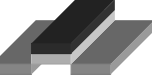
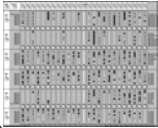


DESIGNING FPGAS & ASICS

Component Reuse

Prof. Don Bouldin, Ph.D.

Electrical & Computer Engineering
University of Tennessee
TEL: (865)-974-5444
FAX: (865)-974-5483
dbouldin@tennessee.edu



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COURSE OUTLINE

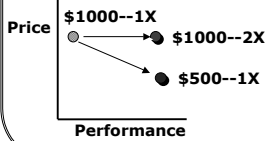
- Overview of FPGAs and ASICs
- Using Synthesis
- HDL Examples
- Simulation and Testing
- Physical Place and Route
- Testing ASICs
- Component Reuse

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ELECTRONIC PRODUCTS ARE PERVERSIVE AND ALWAYS IMPROVING



Moore's Law: Every 18 months integrated circuit manufacturing can produce 2X performance for the same price or the same performance for half the price.

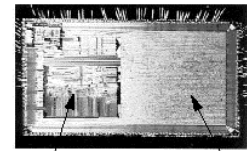


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Design Example

Nokia 9000 wireless phone/PDA

Nokia 9000



Embedded μ P Core 90K CBA gates

- ◆ Personal digital assistant (PDA) and GSM cellular phone
- ◆ Embedded block imported into a CBA foundation
- ◆ "Required 2 Mask Designers instead of 20"

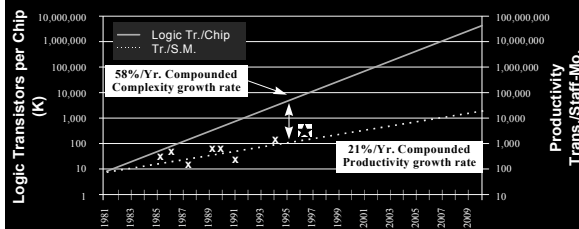
CR: Design with FPGAs/Block4/10/97

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SYNOPSYS

DESIGN PRODUCTIVITY LAGS MANUFACTURING CAPABILITY

The Impending Design Productivity Crisis

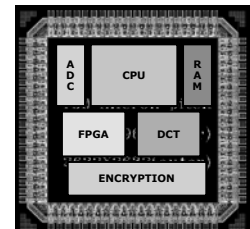


Maya Rubelz USAF Wright Labs maya.rubelz@sn.wpafb.af.mil http://rassp.scra.org

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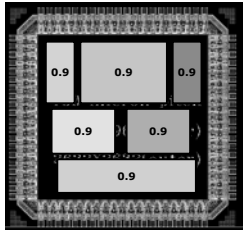
A SYSTEM-ON-CHIP CAN REUSE COMPONENTS

- EACH COMPONENT MUST BE "KNOWN GOOD"
- DETAILED INFORMATION IS REQUIRED FOR SUCCESS
- BEST WHEN COMPONENTS ARE DESIGNED FOR REUSE

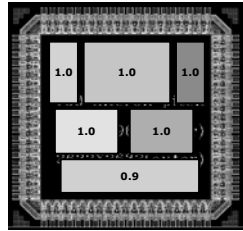


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UNPROVEN COMPONENTS AND INTERCONNECT ARE RISKIER AND MORE TIME-CONSUMING TO VERIFY



Interconnect 0.9 so
 $0.9 \times 0.9 \times 0.9 \times 0.9 \times 0.9 \times 0.9 \times 0.9$
 $= 0.5$

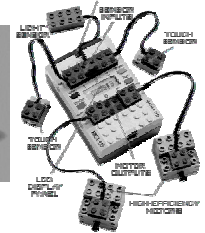
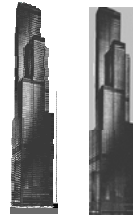


Interconnect 1.0 so
 $1.0 \times 1.0 \times 1.0 \times 1.0 \times 1.0 \times 1.0 \times 1.0$
 $= 1.0$

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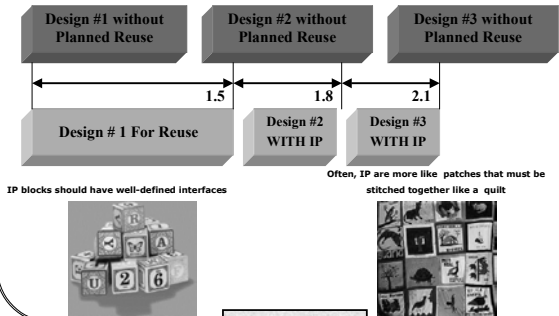
WE BUILD SKYSCRAPERS USING STANDARDIZED BLOCKS

So, let's use standardized blocks to build systems



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DESIGN WITH REUSE CAN HAVE A SIGNIFICANT IMPACT



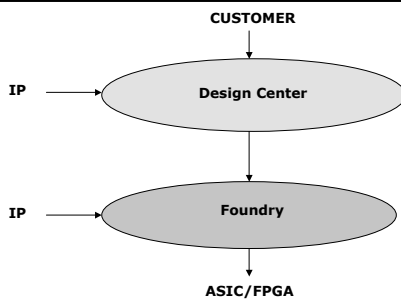
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REQUIREMENTS FOR REUSABLE IP

- **BASICS:**
 - HDL Models
 - Functional Description
 - Application Intent
 - Interface Specifications
 - Authors and Owners
 - Size, Delay, Power Estimates
 - Packaging Info
- **ALSO NEED:**
 - Test Bench (Input Stimuli/Output Responses)
 - Tools and Versions Used/Needed
 - Foundry Used For Fab
 - Size, Delay, Power Measurements
 - Testability Features (BIST, JTAG, SCAN)

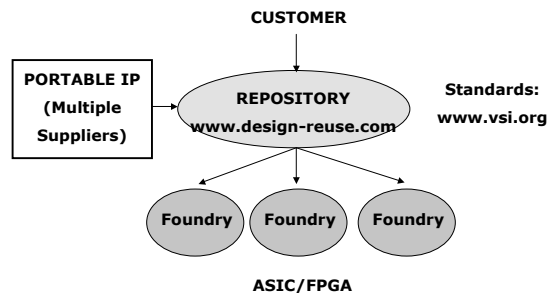
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LOW-RISK IP CAN ATTRACT BUSINESS BUT PRICES MAY NOT BE COMPETITIVE



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AN OPEN COMPETITIVE MARKET HAS BEEN INITIATED



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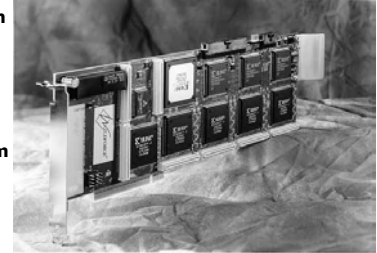
MARKETPLACE EXPERIENCES

- **STAR IP:**
Blocks requiring 100+ staff years to design (like ARM, MIPS) have become bestsellers and come with lots of support.
- **Small IP:**
Blocks requiring 1-2 staff years to design are priced at 1/3 of the development cost. Buyers are skeptical about the value and often prefer to do these in-house.
- **Medium IP:**
Blocks requiring 5-10 staff years are profitable for both seller and buyer. However, some suppliers have been bought by foundries to add to the foundries' captive portfolios.

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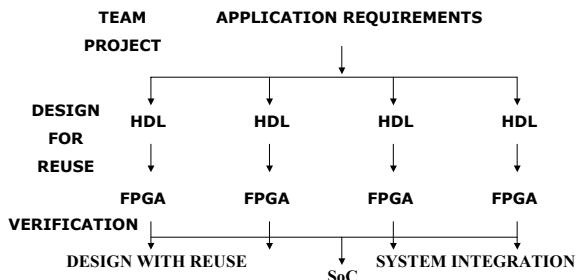
RECONFIGURABLE FPGA-BASED BOARDS CAN PROTOTYPE DIGITAL DESIGNS

- FPGAs can contain soft or hard IP (including CPUs).
- www.atmel.com
- www.altera.com
- www.triscend.com
- www.xilinx.com



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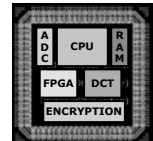
DESIGN-FOR-REUSE and DESIGN-WITH-REUSE



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SUMMARY

- We must reuse previous designs to exploit IC manufacturing.
- Designs must be well-documented and well-understood.
- Design-for-reuse and design-with-reuse take time and effort.
- Verification can be done using simulation and prototyping.
- Proven components can be verified in less time.
- Platform design can reduce risk and attract business.
- Digital and analog designs can be prototyped using reconfigurable systems.
- FPGA chips can contain soft or hard CPU cores.
- Multi-project brokers provide inexpensive state-of-the-art fabrication.



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